

iC-OG BLCC OGC

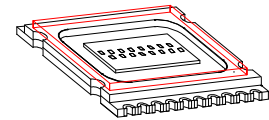
OPTO ENCODER PACKAGE SPECIFICATION



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ORDERING INFORMATION

Type	Package	Options	Order Designation
iC-OG	BLCC OGC	----	----
iC-OG	BLCC OGC	Glass Lid	iC-OG BLCC OGC-OG1L
iC-OG	BLCC OGC	Reticle	iC-OG BLCC OGC-OGxR

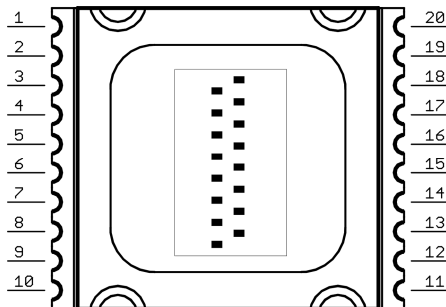


8.2 mm x 9.5 mm
RoHS compliant

PIN CONFIGURATION

PIN FUNCTIONS

(top view)



No.	Name	Function
1	CSR	External Capacitor for LED Control
2	NI0	Track 0 Analog Push-Pull Output
3	NI1	Track 1 Analog Push-Pull Output
4	NI2	Track 2 Analog Push-Pull Output
5	LED	LED Driver Output
6	AGND	Reference Ground for ISET and CSR Circuitry
7	ISET	LED Current Control Setup
8	TIN	Negative Test Aid Input
9	TIP	Positive Test Aid Input
10	NER	Error Message Output, low active
11	GND	Ground
12	S7	Track 7 Push-Pull Output
13	S6	Track 6 Push-Pull Output
14	S5	Track 5 Push-Pull Output
15	S4	Track 4 Push-Pull Output
16	S3	Track 3 Push-Pull Output
17	S2	Track 2 Push-Pull Output
18	S1	Track 1 Push-Pull Output
19	S0	Track 0 Push-Pull Output
20	VCC	+5V Supply Voltage

ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Parameter	Conditions	Fig.	Min. Typ. Max.			Unit
					Min.	Typ.	Max.	
TG1	Ta	Operating Ambient Temperature Range (extended temperature range on request)			-20		90	°C
TG2	Ts	Storage Temperature Range			-30		110	°C
TG3	Tpk	Reflow Soldering Peak Temperature	tpk < 20 s, convection reflow (not suitable for vapour phase soldering) TOL (time on label) 8 h; please refer to customer information file No. 7 for details				260	°C

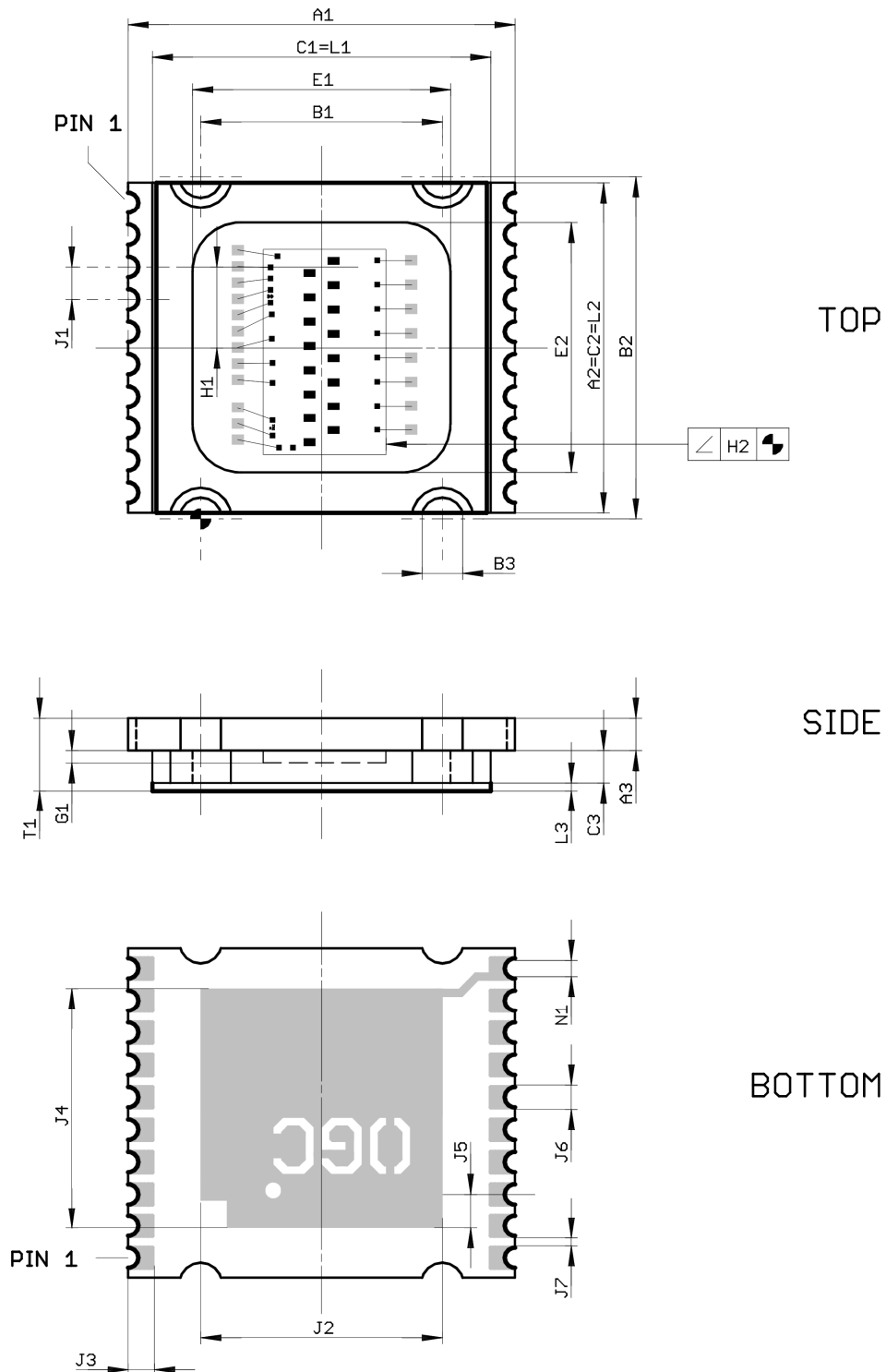
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PHYSICAL DIMENSIONS



DRA_OGC1_PACK_1

DIMENSION TABLE

Item	Parameter	Comments					Unit
			Min.	Typ.	Max.	Tolerance	
Substrate and Holes							
A1	Outline X			9.5		±0.1	mm
A2	Outline Y			8.2		±0.1	mm
A3	Substrate Thickness	bottom package to bottom die	0.710	0.8	0.971		mm
B1	Hole Distance X			6.0		±0.05	mm
B2	Hole Distance Y			8.5		±0.05	mm
B3	Thruhole Diameter ¹⁾			1.0		+0.05	mm
Frame Size and Shape							
C1	Frame Outline X	equivalent to L1		8.4		±0.25	mm
C2	Frame Outline Y	equivalent to A2		8.2		±0.25	mm
C3	Frame Thickness		0.707	0.8	0.979		mm
Window Size an Shape							
	Window Edge Radius			1.2			mm
E1	Window Cavity X			6.4		±0.25	mm
E2	Window Cavity Y			6.2		±0.25	mm
Chip Placement							
G1	Chip Thickness			0.3			mm
H1	Chip Position Y	center of package vs. mid of sensors		2.0		±0.15	mm
H2	Chip Tilt Angle vs. Paddle					±1.6	DEG
Bottom Metal Pattern							
J1	Lead Pitch			0.8		±0.05	mm
J2	Shield Size X			6.0		±0.03	mm
J3	Lead Size			0.65		±0.03	mm
J4	Shield Size Y			5.95		±0.03	mm
J5	Shield Position vs. Lead			0.85		±0.075	mm
J6	Lead Size			0.6		±0.03	mm
J7	Lead-Lead Spacing			0.2		±0.03	mm
N1	Lead PTH	remaining inner diameter		0.4		+0.1	mm
Glass/Reticle Cover							
L1	Glass/Reticle Size X			8.2		±0.1	mm
L2	Glass/Reticle Size Y			8.2		±0.1	mm
L3	Glass/Reticle Thickness	glass lid OG1L reticle OGxR		0.20 0.50			mm mm
	Position Glass Lid vs. Chip					±0.3	mm
Thickness Specifications							
T1	Overall Thickness	bottom substrate to top of glass bottom substrate to top of reticle	1.61 1.91		2.18 2.48		mm mm

Notes:

1) The frame lamination process does not ensure that thruholes remain free of excessive glue.

REVISION HISTORY

Rev	Notes	Pages affected
A1	Initial version	
B1	Complete revision, particularly with regard to revision of Absolute Maximum Ratings (TG3) Reflow Soldering	all
B2	Ordering Information update; Absolute Maximum Ratings: Reflow Soldering Peak Temperature: Conditions; Dimension Table: Item B3 Notes; Items L3, T1 supplemented; Assembly Part List omitted; Disclaimer update	1, 3, 4

GENERAL HANDLING INSTRUCTIONS

After opening the dry pack, devices must be mounted within 8 hours (in factory conditions of maximum 30 °C / 60 % RH) or must be stored at < 10 % RH. Devices require baking before mounting if the Humidity Indicator Card shows > 10 % when read at 23 °C ± 5 °C or if the conditions mentioned above are not met. Devices may be baked for 72 hours at 100 °C using high temperature device containers (trays).

Samples

Samples may not be subject for dry pack delivery, and, in that case, are not intended for reflow soldering.

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